# CINDAS LLC

#### **Industry Benchmark for Critically Evaluated Materials Properties Data**

# Now available on-line—CINDAS Microelectronics and Composite Materials Database (MCMD)

The Microelectronics and Composite Materials Database (MCMD) is a searchable, browsable online database that contains data about thermal, mechanical, electrical and physical properties of microelectronics packaging materials; it also contains data on composite materials, including ceramic matrix composites (particulate, whisker reinforced and GLARE materials). The MCMD database contains 1,527 materials, 671 properties and contains over 32,873 data curves.

Its predecessor, the MPMD (Microelectronics Packaging Materials Database) was developed under the sponsorship of the Semiconductor Research Corporation (SRC). The MCMD replaced the MPMD in January 2023.

### Search and Browse the

# Microelectronics Packaging Materials Database

Material Group (Adhesives, Ceramics, Unfilled Epoxies, Semiconductors, etc.) Material Name (Silver-Filled Epoxy, Iron Aluminides Intermetallics, Germanium, etc.) Property Group (Electrical, Mechanical, Thermophysical, Optical, etc.) Property Name (Dielectric Constant, Leakage Conductance, Elastic Modulus, etc.)

#### Access

Costs of subscriptions to the CINDAS databases depend on the number of locations and the number of potential users at each location. Once subscribed, engineers, librarians, researchers, and scientists all have unlimited access to the databases by IP address/ ranges.

#### Interface Tools

Save – data for further analysis.

Copy – graphs with ease into PowerPoint.

Project and Manipulate – the database content live.

#### **Interface Features**

Find – material group or property group by browsing, or material name or property name by searching.

- View the effects on a given property with changes in temperature or other independent variable.
- Compare multiple data curves of different materials on a single graph.
- References are available for every graph and description in the show text feature.

#### **Complete Packages**

The most complete package for research and applications includes:

- ASMD Aerospace Structural Metals Database
- HPAD High Performance Alloys Database
- AHAD Aerospace and High Performance Alloys Database (combines ASMD and HPAD)
- CLTD Cryogenic and Low Temperatures Database
- TPMD Thermophysical Properties of Matter Database
- MCMD Microelectronics and Composite Materials Database

The CINDAS databases give the composition and describe the test conditions of each material. They also present specific conditions for each desired material plotted on a graph.

Learn more at https://cindasdata.com/resources

# Searching and Browsing: Microelectronics and Composite Materials Database (MCMD) Finding Information

Search: Enter the full or partial name of the property or material.

Browse: Use the drop-down menu to find the property or material.

The Microelectronics and Composite Materials Database contains 1,527 materials in 40 material groups and 671 properties in 15 property groups.

MCMD (version 1, data updated 2022.12) Start Over | TOC | Help Browse By: Search By: Material Group Material Name ~ Type material name here Go e.g., ni inco, Nickel Incoloy 0 or Property Group Property Name ~ Type property name here e.g., electric, Electric Resistivity Go MCMD (version 1, data updated 2022.12) Select Property Group Thermophysical Properties ¥ (13 property groups) Select Property Name: Coeft of Thermal Expansion Coeff of Thermal Expansion (2) CINDAS LLC, The Com Contact Angle Phone +1 755 507-540 Coupling Coefficient, Thermal Coupling Coefficient, Thermal D. West Lafayatte. IN 47906-3445 Email into@condimitate Gross-Linking Density © 2023 CINDAS LLC | Cure Degree Cure Temperature Curie Temperature in 📩 Density Density, kg m[-3] Enthalpy Glass Transition Temperature Glass Transition Temp (Master Curve) Increase in Thermal Conductivity Initial Zero-Shear Viscosity Interfacial Tension Lattice Parameter Linear Shrinkage

# **Customizing Information**

Select: The independent variable.

Select Property Group	hemoph	rysical Propertie	5	¥
and a second second (	3 proper	ty groups)		
Select Property Name: [	Cure Deg 5 proper		*	
Property Range				
Cure Degree (percent)0	0 - 100 0			
Select an Independent V	ariable, a	nd then click th	e Show Graph or Show Text I	sutton
Independent Variable	Minimum	Maximum		
O Cure Temperature (K)	373.0	448.0		
O Cure Time (h)	0.03	53.2		
O Temperature (K)	323.0	443.0		

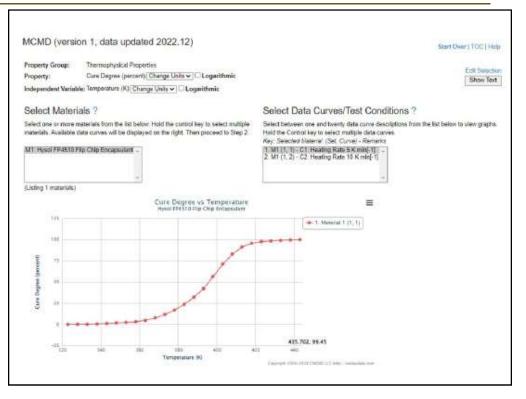
The Convergence Center, 101 Foundry Drive Suite 4700, West Lafayette IN 47906-3445 USA Phone: 765-807-5400 • 765-807-7011 • Fax: 765-807-5291 • info@cindasdata.com • www.cindasdata.com

## **Viewing Information**

The MCMD allows the user to view a property of multiple materials on one graph.

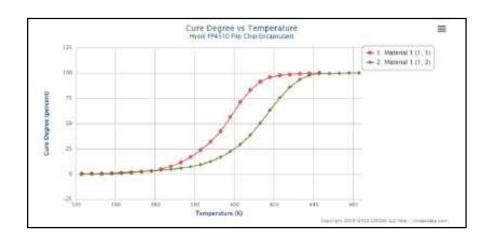
- Step 1: Select Materials.
- Step 2: Select Data Curves or Test Conditions.

Note: At any time, the user can click on the "Show Text" button to see the values of the data points, text description, references, etc.



#### **Results: Graphic and Numeric**

- Over 32,870 data curves
- Color-coded data curves
- Multiple curves of different materials per graph
- Hovering cursor to show X and Y values at each data point
- Unit conversion package
  - Contains both English and SI units
  - Shows all typically used units for the variables
  - Allows both X-axis and Yaxis selection



#### Material Groups

The MCMD has 1,527 materials classified into 40 material groups. The MCMD can be searched by material or property name. If the full name is used to search, the search will bring the user directly to that material. If a partial name is used, the search will return the closest matches.

Material Groups	Number	
Adhesives	30	
Ceramics - High K Oxides		
Ceramics - Nitrides, Silicides, Carbides,		
Ceramics - Others		
Ceramics - Oxides	34	
Cermets	3	
Coating and Unfilled Epoxies	25	
Coating: Thermal Barrier	24	
Composite Components: Fiber, Filler, Reinforcement and Matrix	16	
Composites - 3D printed-Additive Manufacturing	11	
Composites - Ceramic Matrix, Fiber-Reinforced	1	
Composites - Ceramic Matrix, Particulate-Reinforced	53	
Composites - Ceramic Matrix, Wisker-Reinforced	40	
Composites - Ceramics Matrix	5	
Composites - from 3DP (3D Printing) Waste	5	
Composites - Kevlar Fiber	52	
Composites - Laminates (Glass/Epoxy, Fiber/Metal)	94	
Composites - Laminates (Others)	166	
Composites - Laminates (Polymer Matrix)	19	
Composites - Metal Matrix	35	
Composites - Nano and Graphene	92	
Composites - Others	63	
Composites - Polymer (Epoxy, Resin) Matrix	32	
Composites - Thermal Management	27	
Compounds, Molding	55	
Elements	33	
Encapsulants and Underfill Materials	27	
Intermetallics, Aluminides	66	
Intermetallics, Beryllides	35	
Intermetallics, Miscellaneous	50	
Intermetallics, Silicides	30	
Liquids & Gases	5	
Metal Alloys	60	
Metal Alloys, Additive Manufacturing	3	
Miscellaneous Materials	2	
Polymers - Others	35	
Polymers - Polyimides/Polyamides	55	
Semiconductors & Optical/Sensor Materials	60	
Solders - Lead Free	57	
Solders - Leaded	41	

#### **Property Groups**

The MCMD contains 671different properties. These properties are separated into 15 easy-tonavigate property groups. Alternatively, you can search the property names by using keywords which would bring you directly to the property you are seeking.

Property Type	Number
Thermophysical Properties	77
Thermoradiative Properties	14
Electrical/Electronic Properties	94
Mechanical Properties - Modulus	71
Mechanical Properties - Strength	57
Mechanical Properties - Stress	36
Mechanical Properties - Hardness	11
Mechanical Properties - Fatigue	10
Mechanical Properties - Creep	9
Mechanical Properties - Strain, Deformation, Strain rate, Area reduction	51
Mechanical Properties - Others	79
Mechanical Properties - Strength, Relative/Ratio	3
Optical Properties	21
Other Properties	137

#### We Are Confident in Our Products

The MCMD is quick, efficient, and frequently updated, and is currently used by a growing list of universities, corporations and research facilities. Please visit www.cindasdata.com for a demo.